

# RTC-700T

## Environment Test Report

Report NO: 13R020001

Summary	<p><input checked="" type="checkbox"/> <b>Pass</b></p> <p><input type="checkbox"/> <b>Fail</b></p> <p>Note : There is/are ____ defect(s) not list in the report, please check it in the DTS Website.</p> <p><input type="checkbox"/> <b>Pass with Deviation</b></p> <p>Comment: _____</p>
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Issue date

2013-04-16

Approval

Tom Lin

Test Engineer

Rex Chang

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## Testing Result

Num	Test item list	Result	Remark
1	Temp./humidity power on/off test	Pass	
2	Room temperature test	Pass	
3	Temperature rise test	Pass	
4	High temperature storage test	Pass	
5	High temperature operation test	Pass	
6	Low temperature storage test	Pass	
7	Low temperature operation test	Pass	
8	Humidity test	Pass	
9	Temperature shock operation test	Pass	
10	Temperature shock non-operation test	Pass	
11	Cold start and hot start test	Pass	

# Configuration of EUT

<b>Test Product: RTC-700T</b>		
<b>Sample Configuration &amp; Quantity Under Test:</b>		
<b>Num</b>	<b>Item</b>	<b>Spec</b>
RTC-700T		
01.	<b>CPU:</b>	Intel® Atom™ Z670 Processor / 1.5GHz
02.	<b>PCBA</b>	RTC-700T A1.2
03.	<b>BIOS</b>	BIOS (V1.2) EC (V1.4)
04.	<b>Memory</b>	DDRII 1GB SDRAM/ Hynix.H5PS1G83EFR-S6C
05.	<b>mSATA</b>	Intel® SSD 40GB / SSDMAEMC040G2
	<b>3G</b>	HUAWEI EM820W
06.	<b>WLAN + BT Module</b>	FangTec. RTL8188CU88
07.	<b>LCD</b>	7" TFT LCD / Hydix.HV070WS1-100 (1024x600)
08.	<b>Touch Panel</b>	7" CPT Touch/ EMERGING DISPLAY.EP0700MLJ5
09.	<b>Battery</b>	JHT.JHT-795RTC70-A(J1067-1), 2S1P 3700mAh
10.	<b>AC Adapter</b>	LTE.LTE24E-S2-2C6 (Output: 12V / 2A)
11.	<b>AC Power Input</b>	110~240V / 60 Hz
12.	<b>Test Software</b>	Windows Embedded 7 / Run PassMark BurnIn Test 7.0 Pro

# Temp./humidity power on/off test

**Test Date:** 03-19~20-2013

**Test Model:** RTC-700T Main Board only

**Test Site:** AAEON QE Dept.

**Test Standard:** Refer to IEC 68-2-30 Testing procedures  
 Test Db: Damp Heat Test  
 Refer to IEC 68-2-1 Testing procedures  
 Test Ab: Cold Test

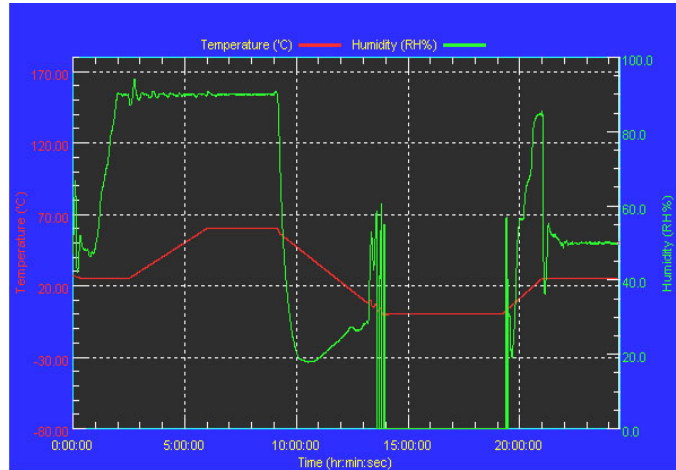
**Test Equipment:**  
 Programmable Temperature & Humidity Chamber  
 K.SON. INS. TECH. CORP.  
 Model: THS-B6T-150+LN2  
 Date of Calibration: 06/11/12  
 Serial Number: 9095KT

**Temperature & Humidity Power On/Off Test:**

**Testing Specification:**

Step	Temperature (°C)	Humidity (%RH)	Duration (HH:MM)
1	25	50	00:30
2	25	50	00:30
3	25	90	01:00
4	25	90	00:30
5	60	90	03:30
6	60	90	03:00
7	0	0	04:50
8	0	0	05:23
9	25	50	01:47
10	25	50	03:00

**Test Curve:**



**Test Result:**

No issues were found during the temperature & humidity power on/off test.

Test Method	Actual	Successful	Failure rate
Power On/Off	1075/times	1075/times	0 %

Note: Failure rate need to under 0.2%.

# Room Temperature test

---

**Test Date:** 04-15-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

**Temperature Measurement:**

40 Channel Thermal Recorder:  
YOKOGAWA Inc,  
Model: DA100-13-1D  
Date of Calibration: 10/08/12  
Serial Number: 12A323190

**Test Condition:**

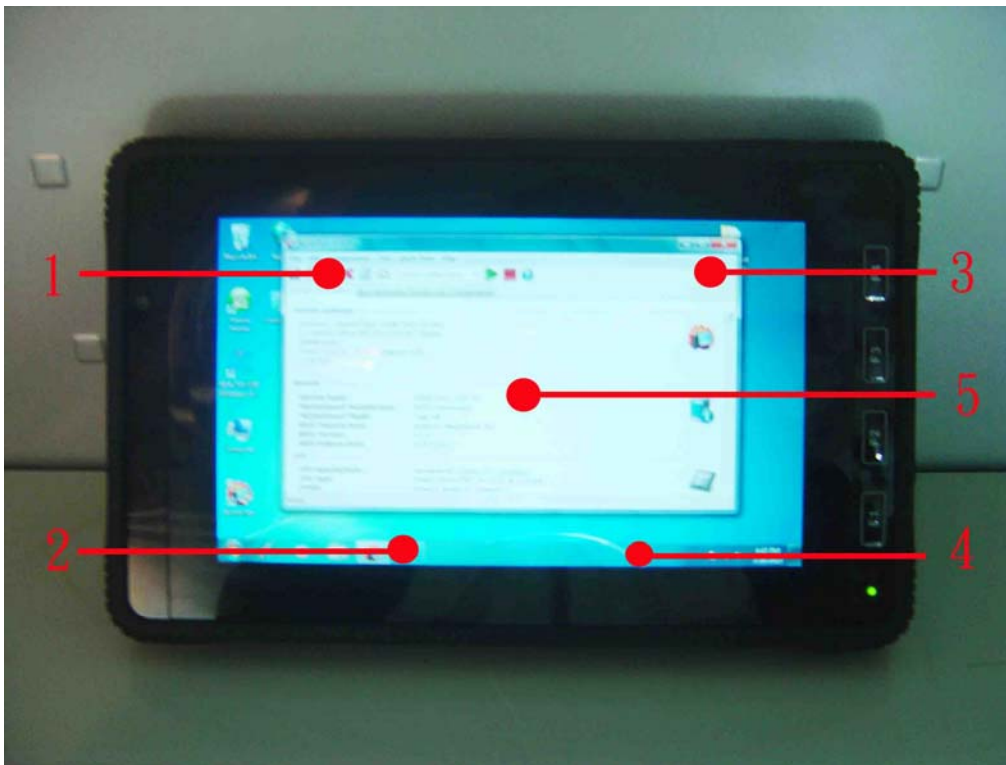
Ambient temperature: 25°C  
Continuous running till thermal stability (within less than 1°C)

**Test Software:**

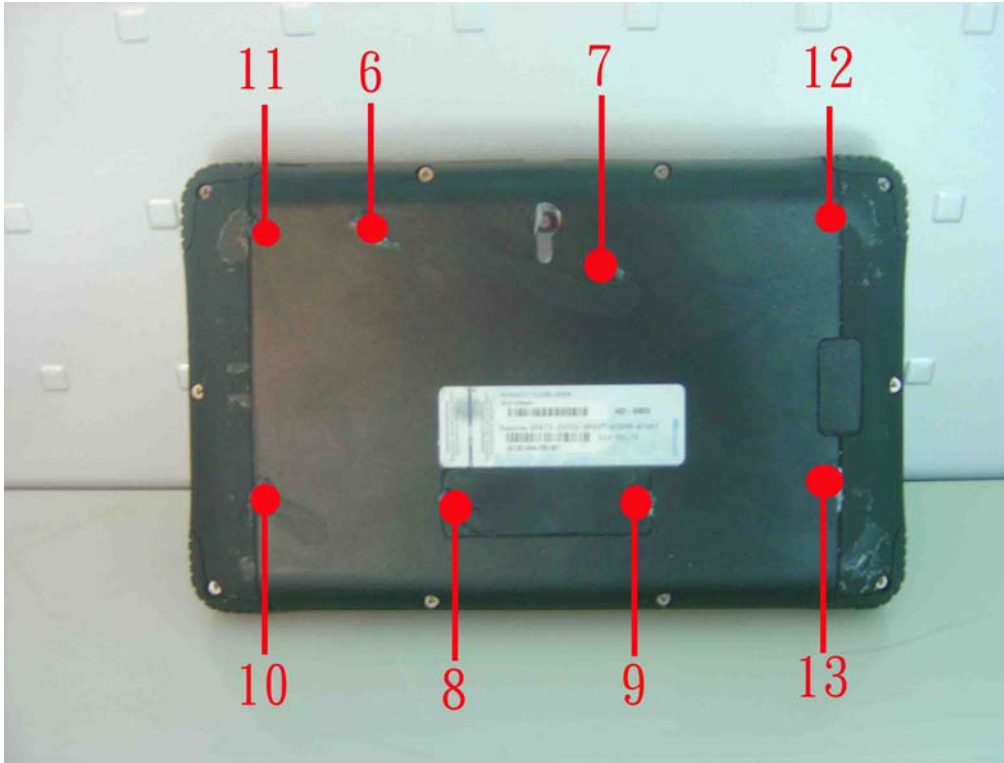
Windows Embedded 7 / Run PassMark Burn In Test 7.0 Pro

**Terminal Recorder:**

Measuring Thermal Couple Position :



# Room Temperature test



**Thermal profile data:**

**RTC-700T**

Point	Temp. Stage(°C)	Spec	25
1. Point 1		$\Delta T$ $\leq 25$ $^{\circ}C$	39.1
2. Point 2			46.3
3. Point 3			40.8
4. Point 4			48.8
5. Point 5			42.5
6. Point 6 - Bottom of mSATA HDD Module			37.7
7. Point 7 - Bottom of CPU with Heat Sink			38.4
8. Point 8 - Bottom of Battery			40.8
9. Point 9 - Bottom of Battery			40.9
10. Point 10 - Bottom of GPS Module			37.1
11. Point 11 - Bottom of PCBA			35.2
12. Point 12 - Bottom of PCBA			35.8
13. Point 13 - Bottom of 3G Module			35.8
Room Temperature		25.0	

**Any Tm value showed in red words which meaning the value over the Tc degree Cof this device specification.**

**Sample Configuration & Quantity Under Test:**

Quantity: 1 (RTC-700T)

**Test Result:**

No issues were found during the room temperature operation test.

# Temperature rise test

**Test Date:** 04-16-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

**Test Standard:** Refer to EN 61131-2(94), UL508 (94)

**Temperature Measurement:**

40 Channel Thermal Recorder:

YOKOGAWA Inc,

Model: DA100-13-1D

Date of Calibration: 10/08/12

Serial Number: 12A323190

**Test Condition:**

Ambient temperature: 35°C

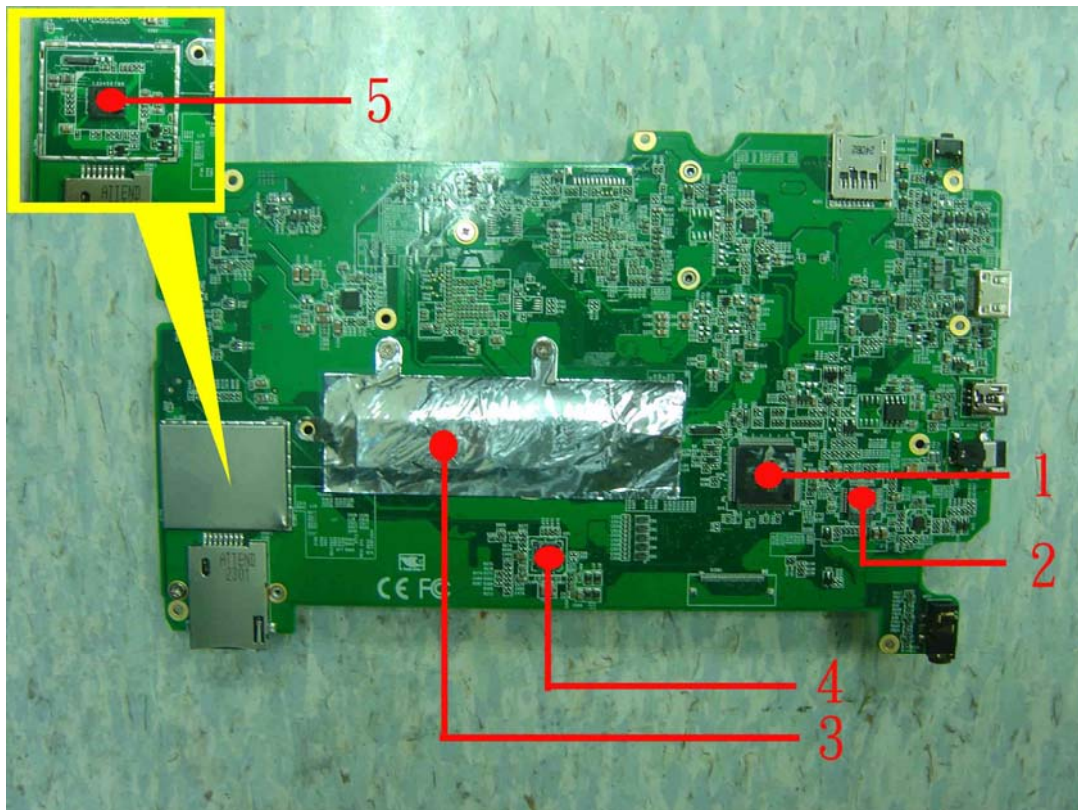
Continuous running till thermal stability (within less than 1°C)

**Test Software:**

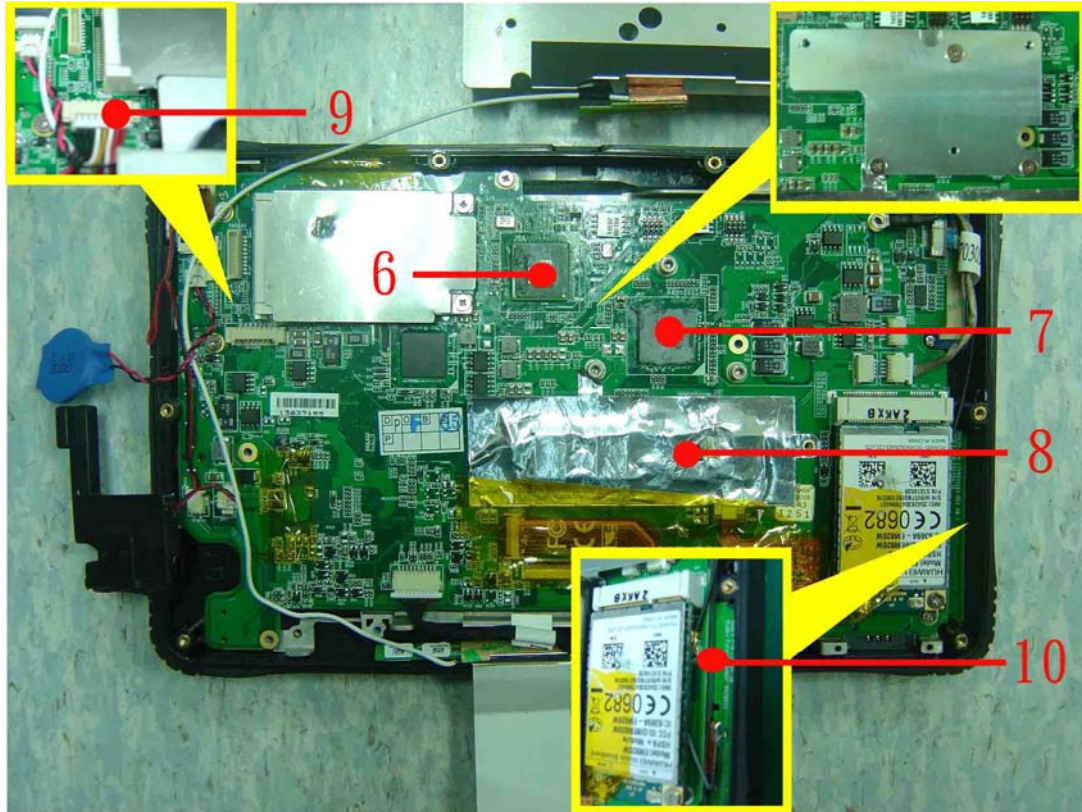
Windows Embedded 7 / Run PassMark Burn In Test 7.0 Pro

**Terminal Recorder:**

Measuring Thermal Couple Position :



# Temperature rise test



## Thermal profile data:

### RTC-700T

Point	Temp. Stage(°C)	Spec	35	25
01. U16 - (TF)Embedded Controller.ITE.IT8516E-L		100	66.5	56.5
02. U47 - (TF) Audio codec.REALTEK.ALC662-GR		100.5	70.6	60.6
03. U10 - RAM Chip		95	65.6	55.6
04. U35 - (TF)USB Hub controller.SMSC.USB2514BI-AEZG		85	67.2	57.2
05. U37 - (TF) GPS Module.BGA50.SMD.u-blox.AMY-6M-0		85	65.0	55.0
06. U12 - (TF)Chipset Whitney Point PCH.INTEL.AF82SM35 SLJ3Q		90	68.3	58.3
07. U1 - (TF)Intel CPU.FCBGA.Lincroft(Oak Trail).1.5GHz.Z670.		90	68.1	58.1
08. U6 - RAM Chip		95	66.1	56.1
09. Inside Air Temperature -Temperature Ambient for mSATA		70	68.8	58.8
10. Inside Air Temperature - 3G Module		70	52.3	42.3
11. Chamber Air Temperature		N/A	35.0	25.0
Any Tm value showed in <b>red words</b> which meaning the value over the Tc degree C of this device specification.				

## Sample Configuration & Quantity Under Test:

Quantity: 1 (RTC-700T)

## Test Result:

No issues were found during the temperature rise operation test.



# High temperature storage test

**Test Date:** 04-02 ~ 09-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

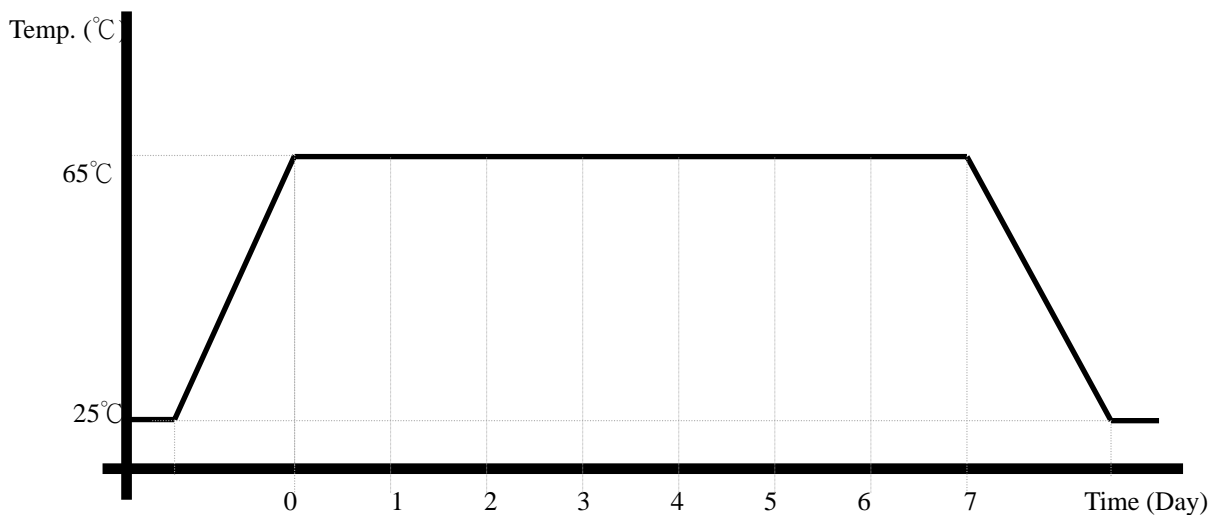
**Test Standard:** Refer to MIL-STD 810G Method 501.5 High Temperature  
Procedure I - Storage

**Test Equipment:**

Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP.)  
Model: THS-B6T-150+LN2  
Date of Calibration: 06/11/12  
Serial Number: 9095KT

**Testing Item:**

1. Test Temperature: 65°C
2. Test Time: 7days
3. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (RTC-700T)

**Test Result:**

No issues were found after the high temperature storage test.

# High temperature operation test

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**Test Date:** 03-27-2013 ~ 04-01-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

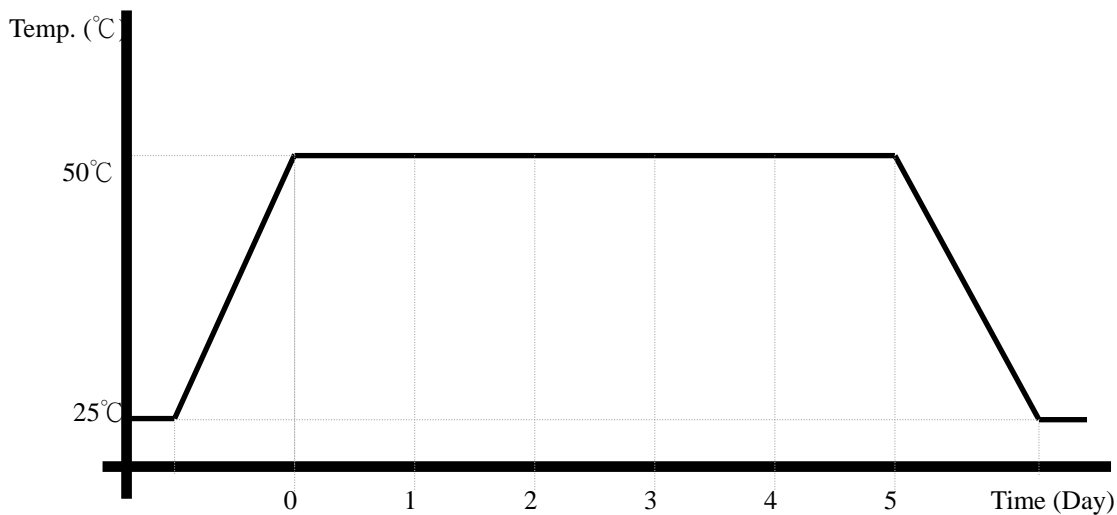
**Test Standard:** Refer to MIL-STD 810G Method 501.5 High Temperature  
Procedure II - Operation

**Test Equipment:**

Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP.)  
Model: THS-B6T-150+LN2  
Date of Calibration: 06/11/12  
Serial Number: 9095KT

**Testing Item:**

4. Test Temperature: 50°C
5. Test Time: 5days
6. Test Software: Windows Embedded 7 / Run PassMark Burn In Test 7.0 Pro
7. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (RTC-700T)

**Test Result:**

No issues were found during the high temperature operation test.

# Low temperature storage test

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**Test Date:** 03-26~27-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

**Test Standard:** Refer to MIL-STD 810G Method 502.5 Low Temperature  
Procedure I - Storage

**Test Equipment:**

Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP.)

Model: THS-B6T-150+LN2

Date of Calibration: 06/11/12

Serial Number: 9095KT

**Testing Item:**

1. Test Temperature: -20°C
2. Test Times: 24Hrs
3. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (RTC-700T)

**Test Result:**

No issues were found after the low temperature storage test.

# Low temperature operation test

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**Test Date:** 04-01~02-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

**Test Standard:** Refer to MIL-STD 810G Method 502.5 High Temperature  
Procedure II - Operation

**Test Equipment:**

Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP.)

Model: THS-B6T-150+LN2

Date of Calibration: 06/11/12

Serial Number: 9095KT

**Testing Item:**

1. Test Temperature: -23°C
2. Test Times: 24Hrs
3. Test Software: Windows Embedded 7 / Run PassMark Burn In Test 7.0 Pro
4. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (RTC-700T)

**Test Result:**

No issues were found during the low temperature operation test.

# Humidity test

**Test Date:** 03-20~26-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

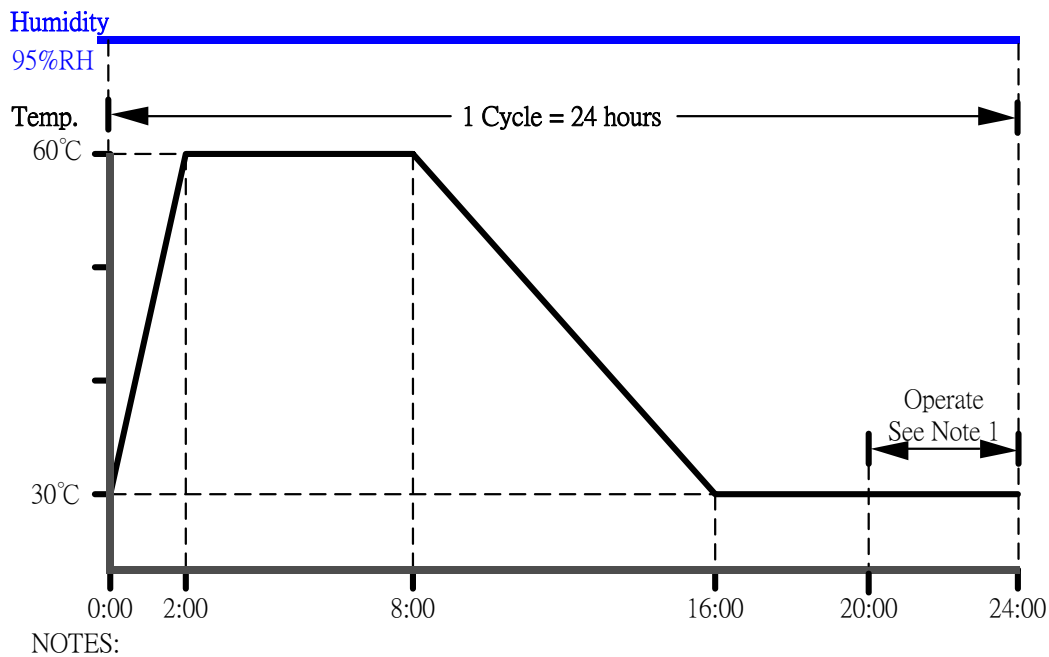
**Test Standard:** Refer to MIL-STD 810G Method 507.5 Testing  
Procedures II – Aggravated Cycle (FIGURE 507.5-7)

**Test Equipment:**

Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP.)  
Model: THS-B6T-150+LN2  
Date of Calibration: 06/11/12  
Serial Number: 9095KT

**Test Condition:**

1. Test Humidity: 95%RH
2. Test Temperature: 60°C / 30°C
3. Test Times: 24Hrs / Cycle
4. Test Cycle: 5 Cycles
5. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (RTC-700T)

**Test Result:**

No issues were found after the humidity storage test.

# Temperature shock operation test

**Test Date:** 04-11~12-2013

**Test Product:** RTC-700T

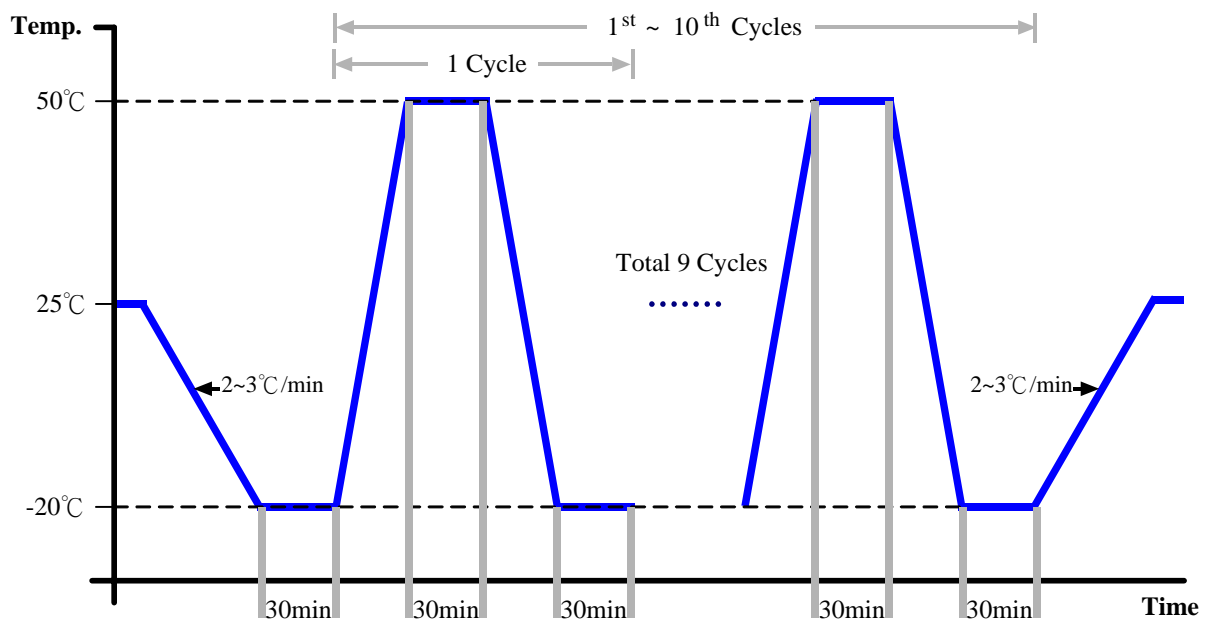
**Test Site:** AAEON QE Dept.

**Test Standard:** Refer to MIL-STD 810G Method 503.5 Temperature Shock  
Procedure I - Shock from constant extreme temperatures

**Test Equipment:**  
Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP.)  
Model: THS-B6T-150+LN2  
Date of Calibration: 06/11/12  
Serial Number: 9095KT

## Test Condition:

1. Test Low Temperature:  $-20^{\circ}\text{C}$
2. Test High Temperature:  $50^{\circ}\text{C}$
3. Test dwell time: 30min
4. Temperature slope: 5 min
5. Test cycle: 10 cycles
6. Test Software: Windows Embedded 7 / Run PassMark Burn In Test 7.0 Pro
7. Test Environment Curve:



## Sample Configuration & Quantity Under Test:

Quantity: 1 (RTC-700T)

## Test Result:

No issues were found during the variation temperature operation test.

# Temperature shock non-operation test

**Test Date:** 04-13~15-2013

**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

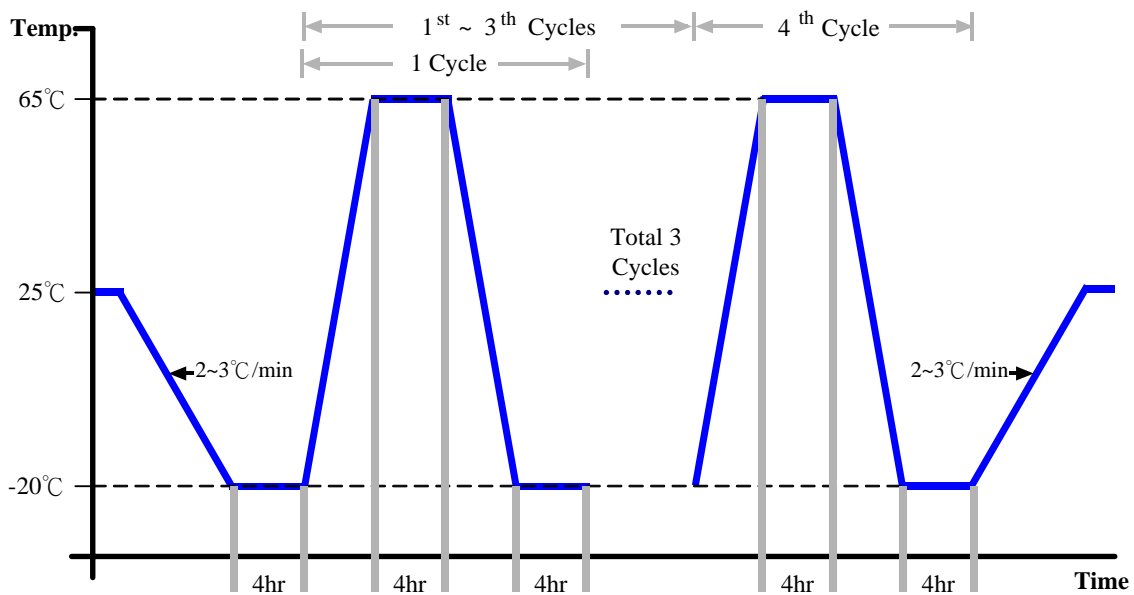
**Test Standard:** Refer to MIL-STD 810G Method 503.5 Temperature Shock  
Procedure I - Shock from constant extreme temperatures

**Test Equipment:**

Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP.)  
Model: THS-B6T-150+LN2  
Date of Calibration: 06/11/12  
Serial Number: 9095KT

**Test Condition:**

1. Test Low Temperature: -20°C
2. Test High Temperature: 65°C
3. Test dwell time: 4Hrs
4. Temperature slope: 10 min
5. Test cycle: 4 cycles
6. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (RTC-700T)

**Test Result:**

No issues were found after the variation temperature non-operation test.

# Cold start and hot start test

**Test Date:** 04-09~10-2013

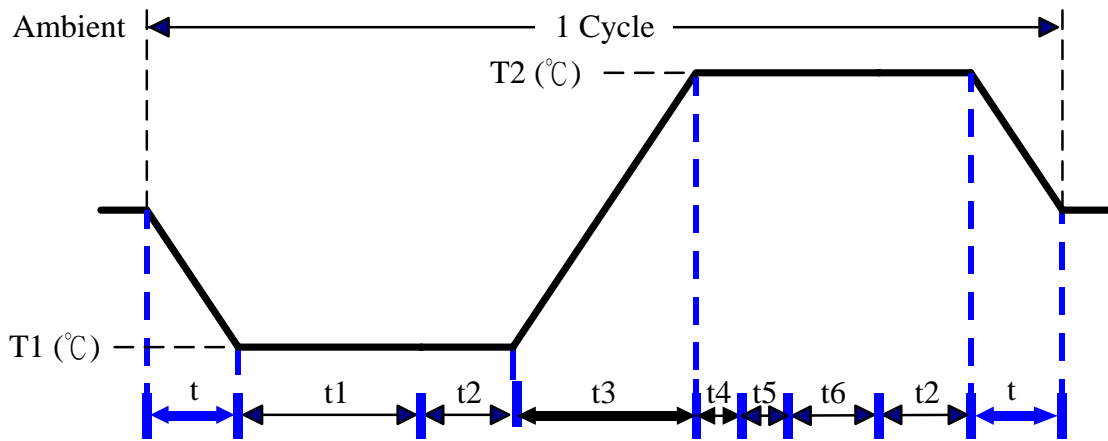
**Test Product:** RTC-700T

**Test Site:** AAEON QE Dept.

**Test Standard:** Refer to IEC 68-2-14 Testing procedures  
Test N: Change of temperature Test

**Test Equipment:**  
Programmable Temperature & Humidity Chamber (K.SON. INS. TECH. CORP).  
Model: THS-B6T-150+LN2  
Date of Calibration: 06/11/12  
Serial Number: 9095KT

**Test Condition:**



Parameters	Description
T1	-25°C
T2	55°C
t1	4 hrs
t2, t6	2 hrs
t4, t5	1hrs
t, t3	2°C/min
n (Cycle)	1

t = temprature slope  
t, t1, t6: Power Off  
t2: Power on/off test 10 times (on 2 min / off 5min)  
t3, t4: Run PassMark Burn In Test  
t5: Win XP Software restart test 3 times  
Test Software: Windows XP

**Test Result:**

- a. No issues were found during the cold start test.
- b. No issues were found during the hot start test.